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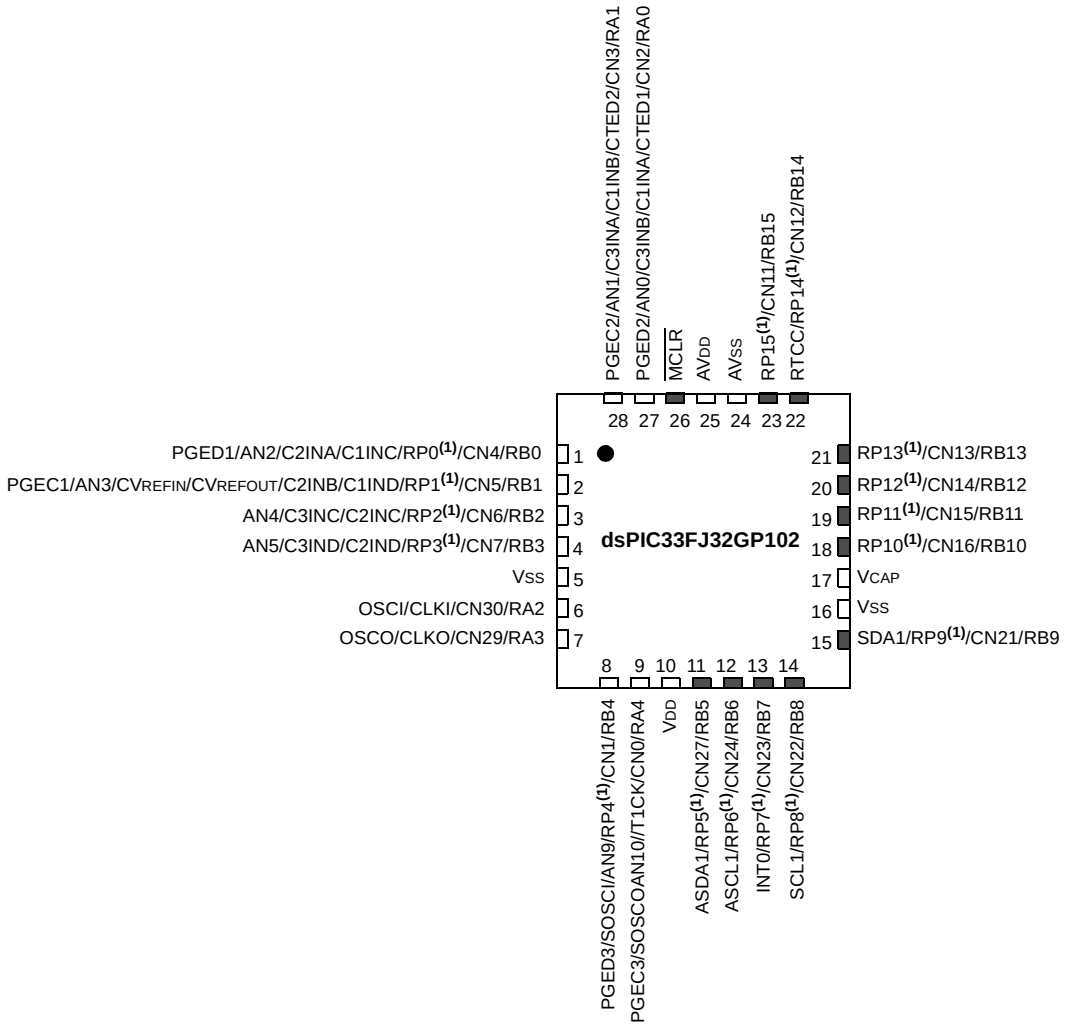
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	15
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16mc101-i-ss

Pin Diagrams (Continued)

28-Pin QFN(2)

■ = Pins are up to 5V tolerant



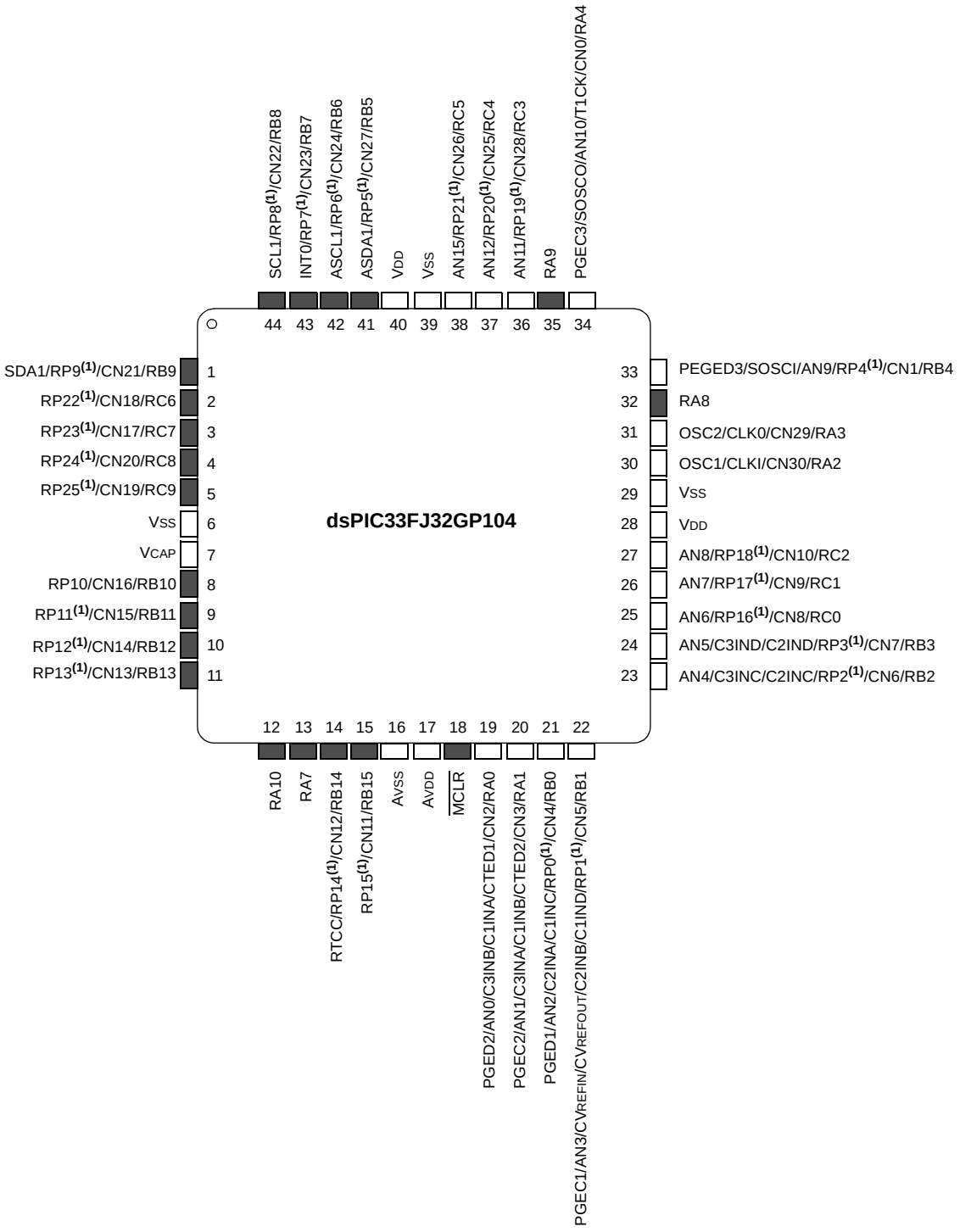
Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

Pin Diagrams (Continued)

44-Pin TQFP

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

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NOTES:

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest *"dsPIC33/PIC24 Family Reference Manual"* sections.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family of 16-bit Digital Signal Controllers (DSCs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, if present on the device
  (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10V-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

The SA and SB bits are modified each time data passes through the adder/subtracter, but can only be cleared by the user application. When set, they indicate that the accumulator has overflowed its maximum range (bit 31 for 32-bit saturation or bit 39 for 40-bit saturation) and will be saturated (if saturation is enabled). When saturation is not enabled, SA and SB default to bit 39 overflow, and therefore, indicate that a catastrophic overflow has occurred. If the COVTE bit in the INTCON1 register is set, the SA and SB bits will generate an arithmetic warning trap when saturation is disabled.

The Overflow and Saturation Status bits can optionally be viewed in the STATUS Register (SR) as the logical OR of OA and OB (in bit OAB) and the logical OR of SA and SB (in bit SAB). Programmers can check one bit in the STATUS Register to determine whether either accumulator has overflowed, or one bit to determine whether either accumulator has saturated. This is useful for complex number arithmetic, which typically uses both accumulators.

The device supports three Saturation and Overflow modes:

- Bit 39 Overflow and Saturation:
  When bit 39 overflow and saturation occurs, the saturation logic loads the maximally positive 9.31 value (0x7FFFFFFFFF) or maximally negative 9.31 value (0x8000000000) into the target accumulator. The SA or SB bit is set and remains set until cleared by the user application. This condition is referred to as ‘super saturation’ and provides protection against erroneous data or unexpected algorithm problems (such as gain calculations).
- Bit 31 Overflow and Saturation:
  When bit 31 overflow and saturation occurs, the saturation logic then loads the maximally positive 1.31 value (0x007FFFFFFF) or maximally negative 1.31 value (0x0080000000) into the target accumulator. The SA or SB bit is set and remains set until cleared by the user application. When this Saturation mode is in effect, the guard bits are not used, so the OA, OB or OAB bits are never set.
- Bit 39 Catastrophic Overflow:
  The bit 39 Overflow Status bit from the adder is used to set the SA or SB bit, which remains set until cleared by the user application. No saturation operation is performed and the accumulator is allowed to overflow, destroying its sign. If the COVTE bit in the INTCON1 register is set, a catastrophic overflow can initiate a trap exception.

3.6.3 ACCUMULATOR ‘WRITE BACK’

The MAC class of instructions (with the exception of MPY, MPY.N, ED and EDAC) can optionally write a rounded version of the high word (bits 31 through 16) of the accumulator which is not targeted by the instruction into data space memory. The write is performed across the X bus into combined X and Y address space. The following addressing modes are supported:

- W13, Register Direct:
  The rounded contents of the non-target accumulator are written into W13 as a 1.15 fraction.
- [W13]+ = 2, Register Indirect with Post-Increment:
  The rounded contents of the non-target accumulator are written into the address pointed to by W13 as a 1.15 fraction. W13 is then incremented by 2 (for a word write).

3.6.3.1 Round Logic

The round logic is a combinational block that performs a conventional (biased) or convergent (unbiased) round function during an accumulator write (store). The Round mode is determined by the state of the RND bit in the CORCON register. It generates a 16-bit, 1.15 data value that is passed to the data space write saturation logic. If rounding is not indicated by the instruction, a truncated 1.15 data value is stored and the least significant word (lsw) is simply discarded.

Conventional rounding will zero-extend bit 15 of the accumulator and will add it to the ACCxH word (bits 16 through 31 of the accumulator).

- If the ACCxL word (bits 0 through 15 of the accumulator) is between 0x8000 and 0xFFFF (0x8000 included), ACCxH is incremented.
- If ACCxL is between 0x0000 and 0x7FFF, ACCxH is left unchanged.

A consequence of this algorithm is that over a succession of random rounding operations, the value tends to be biased slightly positive.

Convergent (or unbiased) rounding operates in the same manner as conventional rounding, except when ACCxL equals 0x8000. In this case, the Least Significant bit (LSb), bit 16 of the accumulator, of ACCxH is examined:

- If it is ‘1’, ACCxH is incremented.
- If it is ‘0’, ACCxH is not modified.

Assuming that bit 16 is effectively random in nature, this scheme removes any rounding bias that may accumulate.

TABLE 4-17: ADC1 REGISTER MAP FOR dsPIC33FJ32(GP/MC)104 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC1 Data Buffer 0																xxxx
ADC1BUF1	0302	ADC1 Data Buffer 1																xxxx
ADC1BUF2	0304	ADC1 Data Buffer 2																xxxx
ADC1BUF3	0306	ADC1 Data Buffer 3																xxxx
ADC1BUF4	0308	ADC1 Data Buffer 4																xxxx
ADC1BUF5	030A	ADC1 Data Buffer 5																xxxx
ADC1BUF6	030C	ADC1 Data Buffer 6																xxxx
ADC1BUF7	030E	ADC1 Data Buffer 7																xxxx
ADC1BUF8	0310	ADC1 Data Buffer 8																xxxx
ADC1BUF9	0312	ADC1 Data Buffer 9																xxxx
ADC1BUFA	0314	ADC1 Data Buffer 10																xxxx
ADC1BUFB	0316	ADC1 Data Buffer 11																xxxx
ADC1BUFC	0318	ADC1 Data Buffer 12																xxxx
ADC1BUFD	031A	ADC1 Data Buffer 13																xxxx
ADC1BUFE	031C	ADC1 Data Buffer 14																xxxx
ADC1BUFF	031E	ADC1 Data Buffer 15																xxxx
AD1CON1	0320	ADON	—	ADSIDL	—	—	—	FORM1	FORM0	SSRC2	SSRC1	SSRC0	—	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG2	VCFG1	VCFG0	—	—	CSCNA	CHPS1	CHPS0	BUFS	—	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0	ADCS7	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
AD1CHS123	0326	—	—	—	—	—	CH123NB1	CH123NB0	CH123SB	—	—	—	—	—	CH123NA1	CH123NA0	CH123SA	0000
AD1CHS0	0328	CH0NB	—	—	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0	CH0NA	—	—	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0	0000
AD1PCFGL	032C	PCFG15	—	—	PCFG<12:0>(1)													0000
AD1CSSL	0330	CSS15	—	—	CSS12:0>(1)													0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The PCFG<10:9> and CSS<10:9> bits are available in dsPIC33FJ32(GP/MC)104 devices only.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1 (CONTINUED)

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

bit 2 **STKERR:** Stack Error Trap Status bit
1 = Stack error trap has occurred
0 = Stack error trap has not occurred

bit 1 **OSCFAIL:** Oscillator Failure Trap Status bit
1 = Oscillator failure trap has occurred
0 = Oscillator failure trap has not occurred

bit 0 **Unimplemented:** Read as '0'

REGISTER 15-9: PxFLTACON: PWMx FAULT A CONTROL REGISTER(1,2,3,4)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	FAOV3H	FAOV3L	FAOV2H	FAOV2L	FAOV1H	FAOV1L
bit 15							bit 8

R/W-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
FLTAM	—	—	—	—	FAEN3	FAEN2	FAEN1
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **FAOV<3:1>H:FAOV<3:1>L:** Fault Input A PWMx Override Value bits
1 = The PWMx output pin is driven active on an external Fault input event
0 = The PWMx output pin is driven inactive on an external Fault input event

bit 7 **FLTAM:** Fault A Mode bit
1 = The Fault A input pin functions in the Cycle-by-Cycle mode
0 = The Fault A input pin latches all control pins to the programmed states in PxFLTACON<13:8>

bit 6-3 **Unimplemented:** Read as '0'

bit 2 **FAEN3:** Fault Input A Enable bit
1 = PWMxH3/PWMxL3 pin pair is controlled by Fault Input A
0 = PWMxH3/PWMxL3 pin pair is not controlled by Fault Input A

bit 1 **FAEN2:** Fault Input A Enable bit
1 = PWMxH2/PWMxL2 pin pair is controlled by Fault Input A
0 = PWMxH2/PWMxL2 pin pair is not controlled by Fault Input A

bit 0 **FAEN1:** Fault Input A Enable bit
1 = PWMxH1/PWMxL1 pin pair is controlled by Fault Input A
0 = PWMxH1/PWMxL1 pin pair is not controlled by Fault Input A

Note 1: Comparator outputs are not internally connected to the PWM Fault control logic. If using the comparator modules for Fault generation, the user must externally connect the desired comparator output pin to the dedicated $\overline{\text{FLTA1}}$ or $\overline{\text{FLTB1}}$ input pin.

2: Refer to Table 15-1 for $\overline{\text{FLTA1}}$ implementation details.

3: The PxFLTACON register is a write-protected register. Refer to **Section 15.3 "Write-Protected Registers"** for more information on the unlock sequence.

4: During any Reset event, $\overline{\text{FLTA1}}$ is enabled by default and must be cleared as described in **Section 15.2 "PWM Faults"**.

REGISTER 20-3: CMxMSKSRC: COMPARATOR x MASK SOURCE SELECT REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	RW-0
—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-8 **SELSRCC<3:0>:** Mask C Input Select bits

1111 = Reserved
1110 = Reserved
1101 = Reserved
1100 = Reserved
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM1H3
0100 = PWM1L3
0011 = PWM1H2
0010 = PWM1L2
0001 = PWM1H1
0000 = PWM1L1

bit 7-4 **SELSRCB<3:0>:** Mask B Input Select bits

1111 = Reserved
1110 = Reserved
1101 = Reserved
1100 = Reserved
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM1H3
0100 = PWM1L3
0011 = PWM1H2
0010 = PWM1L2
0001 = PWM1H1
0000 = PWM1L1

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 device families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Real-Time Clock and Calendar (RTCC)"** (DS70310) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This chapter discusses the Real-Time Clock and Calendar (RTCC) module, available on dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices, and its operation.

Some of the key features of the RTCC module are:

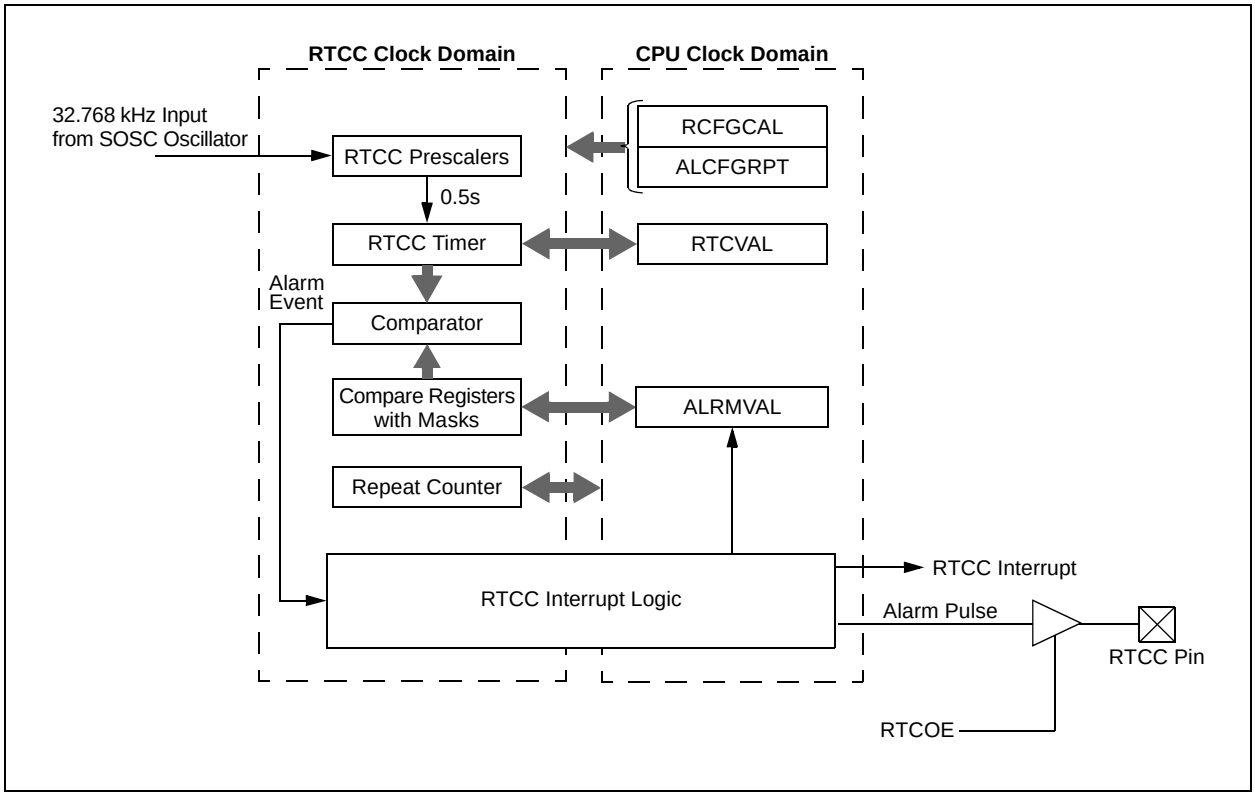
- Time: hours, minutes and seconds
- 24-hour format (military time)
- Calendar: weekday, date, month and year
- Alarm configurable
- Year range: 2000 to 2099
- Leap year correction
- BCD format for compact firmware
- Optimized for low-power operation
- User calibration with auto-adjust
- Calibration range: ±2.64 seconds error per month
- Requirements: external 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

The RTCC module is intended for applications where accurate time must be maintained for extended periods of time with minimum to no intervention from the CPU. The RTCC module is optimized for low-power usage to provide extended battery lifetime while keeping track of time.

The RTCC module is a 100-year clock and calendar with automatic leap year detection. The range of the clock is from 00:00:00 (midnight) on January 1, 2000 to 23:59:59 on December 31, 2099.

The hours are available in 24-hour (military time) format. The clock provides a granularity of one second with half-second visibility to the user.

FIGURE 21-1: RTCC BLOCK DIAGRAM



NOTES:

23.2 On-Chip Voltage Regulator

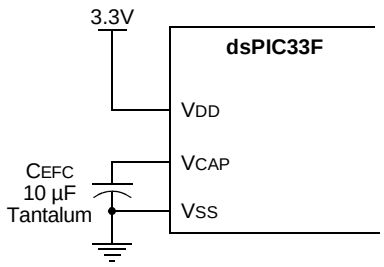
All of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 23-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 26-14 located in **Section 26.1 "DC Characteristics"**.

Note:	It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 μs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 23-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 26-14 located in **Section 26.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for low-ESR capacitors to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

23.3 BOR: Brown-out Reset

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an Oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

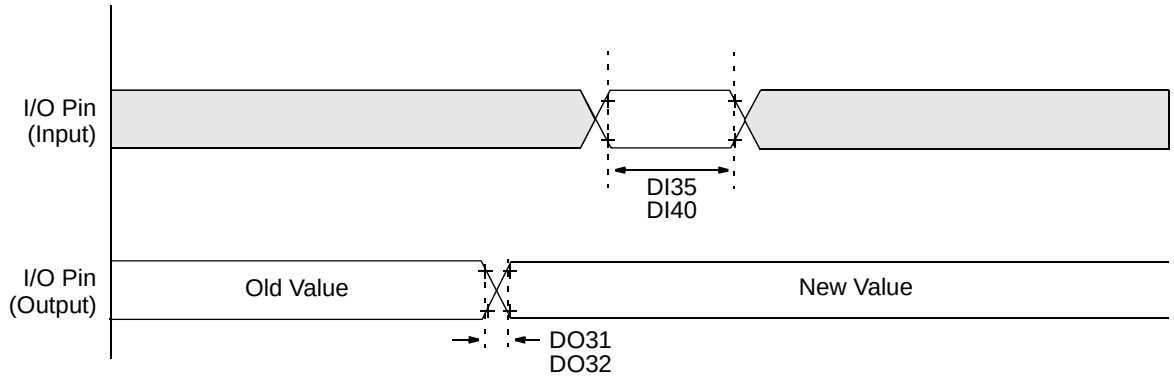
Concurrently, the PWRT Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle modes and resets the device should VDD fall below the BOR threshold voltage.

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF	Wm,Wn	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO	#lit14,Expr	Do code to PC + Expr, lit14 + 1 times	2	2	None
		DO	Wn,Expr	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED	Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC	Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
34	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
36	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
37	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
38	GOTO	GOTO	Expr	Go to address	2	2	None
		GOTO	Wn	Go to indirect	1	2	None
39	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
40	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
41	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z
		IOR	f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
42	LAC	LAC	Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
43	LNK	LNK	#lit14	Link Frame Pointer	1	1	None
44	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
45	MAC	MAC	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd, AWB	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
46	MOV	MOV	f,Wn	Move f to Wn	1	1	None
		MOV	f	Move f to f	1	1	N,Z
		MOV	f,WREG	Move f to WREG	1	1	None
		MOV	#lit16,Wn	Move 16-bit literal to Wn	1	1	None
		MOV.b	#lit8,Wn	Move 8-bit literal to Wn	1	1	None
		MOV	Wn,f	Move Wn to f	1	1	None
		MOV	Wso,Wdo	Move Ws to Wd	1	1	None
		MOV	WREG,f	Move WREG to f	1	1	None
		MOV.D	Wns,Wd	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
		MOV.D	Ws,Wnd	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
47	MOVSAC	MOVSAC	Acc,Wx,Wxd,Wy,Wyd,AWB	Prefetch and store accumulator	1	1	None

FIGURE 26-3: CLKO AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

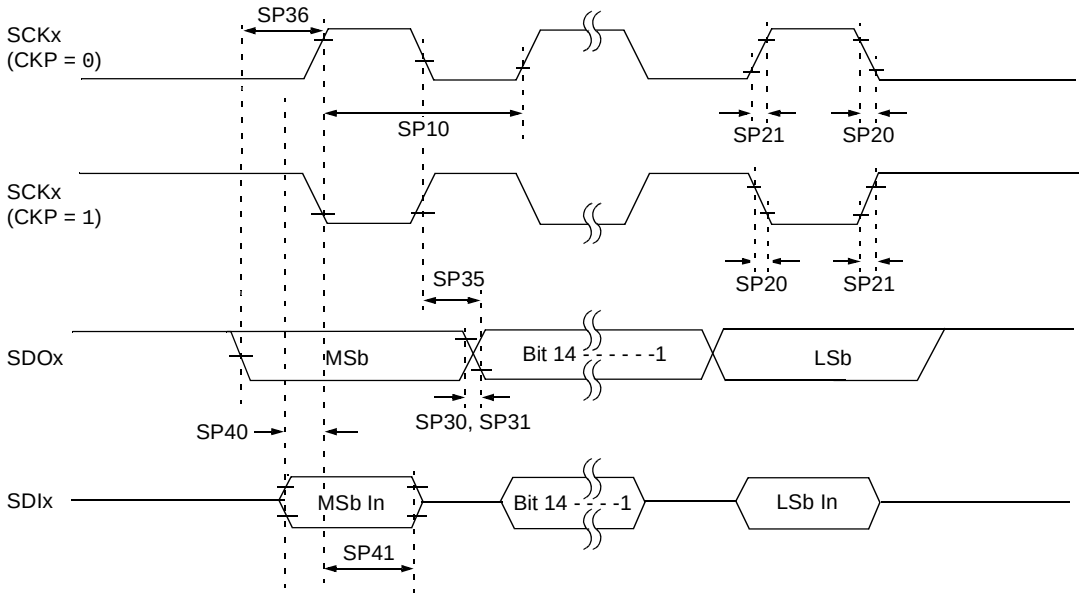
TABLE 26-20: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	
DO32	TIOF	Port Output Fall Time	—	10	25	ns	
DI35	TINP	INTx Pin High or Low Time (input)	25	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: These parameters are characterized, but are not tested in manufacturing.

FIGURE 26-13: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS FOR dsPIC33FJ16(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-31: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	10	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

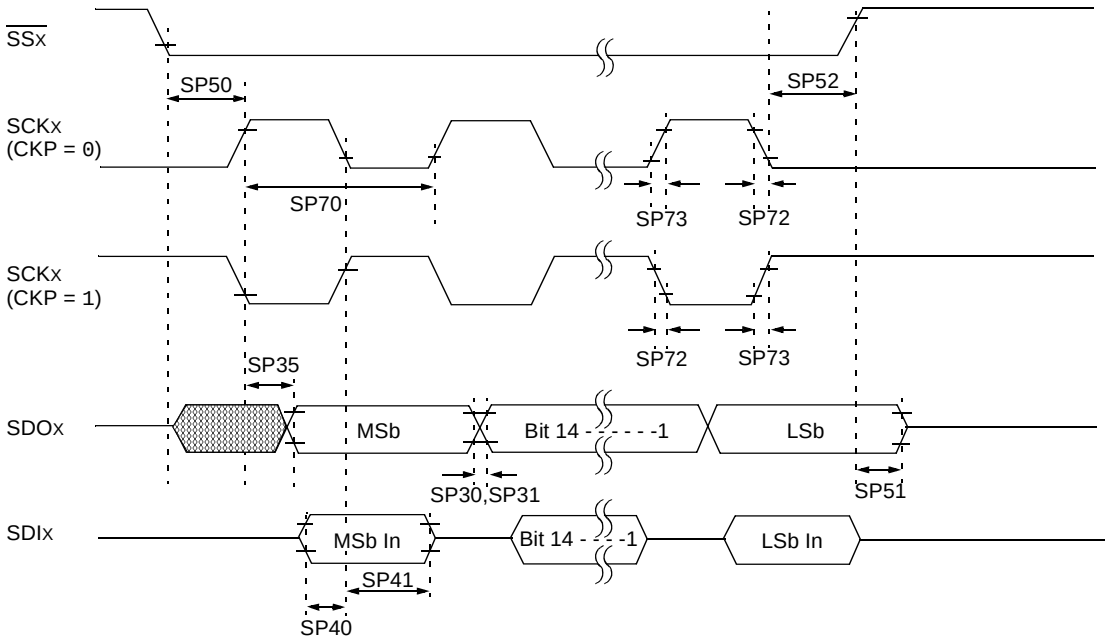
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

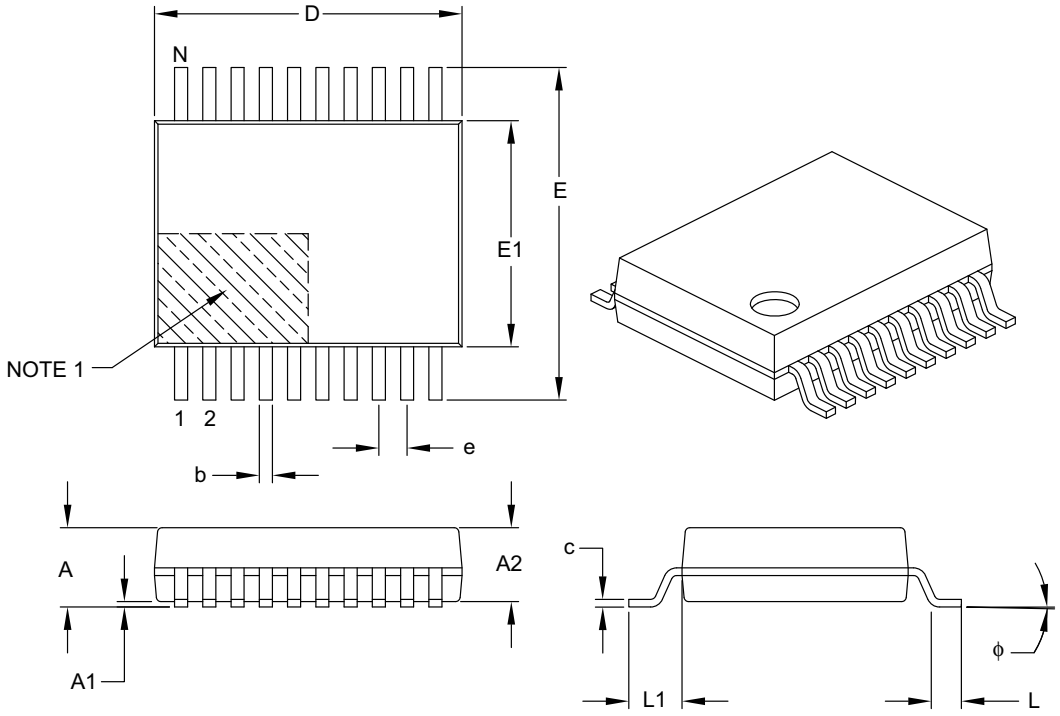
FIGURE 26-25: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

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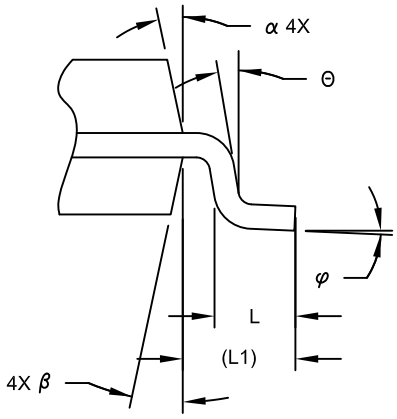
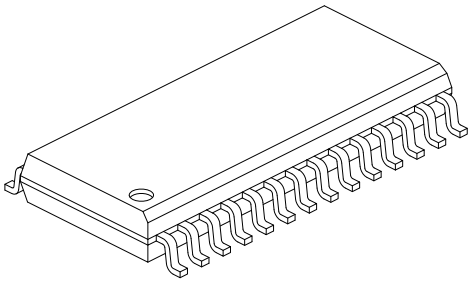
28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

APPENDIX A: REVISION HISTORY

Revision A (January 2011)

This is the initial released version of the document.

Revision B (February 2011)

All major changes are referenced by their respective section in Table A-1.

In addition, minor text and formatting changes were incorporated throughout the document.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
High-Performance, Ultra Low Cost 16-bit Digital Signal Controllers	Pin diagram updates (see **"Pin Diagrams"**): • 20-pin PDIP/SOIC/SSOP (dsPIC33FJ16MC101): Removed the $\overline{\text{FLTB1}}$ pin from pin 10 • 28-pin SPDIP/SOIC/SSOP (dsPIC33FJ16MC102): Relocated the $\overline{\text{FLTB1}}$ pin from pin 12 to pin 14; relocated the $\overline{\text{FLTA1}}$ pin from pin 16 to pin 15 • 28-pin QFN (dsPIC33FJ16MC102): Relocated the $\overline{\text{FLTA1}}$ pin from pin 13 to pin 12; relocated the $\overline{\text{FLTB1}}$ pin from pin 9 to pin 11 • 36-pin TLA (dsPIC33FJ16MC102): Relocated the $\overline{\text{FLTA1}}$ pin from pin 17 to pin 16; relocated the $\overline{\text{FLTB1}}$ pin from pin 10 to pin 15
Section 1.0 "Device Overview"	Added Notes 1, 2, and 3 regarding the $\overline{\text{FLTA1}}$ and $\overline{\text{FLTB1}}$ pins to the Pinout I/O Descriptions (see Table 1-1). Added **Section ""**.
Section 4.0 "Memory Organization"	Updated All Resets value for PxFLTACON and PxFLTABCON to the 6-Output PWM1 Register Map (see Table 4-9). Added Note 1 to the PMD Register Map (see Table 4-29).
Section 6.0 "Resets"	Removed Reset timing sequence information from **Section 6.2 "System Reset"**, as this information is provided in Figure 6-2.
Section 15.0 "Motor Control PWM Module"	Added Note 2 and Note 3 regarding the $\overline{\text{FLTA1}}$ and $\overline{\text{FLTB1}}$ pins to the 6-channel PWM Module Block Diagram (see Figure 15-1). Added **Section 15.2 "PWM Faults"** and **Section 15.3 "Write-protected Registers"**. Added Note 2 and Note 3 regarding the $\overline{\text{FLTA1}}$ and $\overline{\text{FLTB1}}$ pins to the note boxes located below the PxFLTACON and PxFLTBCON registers (see Register 15-9 and Register 15-10).
Section 17.0 "Inter-Integrated Circuit™ (I^2C™)"	Updated the descriptions for the conditional If STREN = 1 and If STREN = 0 statements for the SCLREL bit in the I2Cx Control Register (see Register 17-1).
Section 23.0 "Special Features"	Added the RTSP Effect column to the dsPIC33F Configuration Bits Description (see Table 23-3).
Section 26.0 "Electrical Characteristics"	Added Parameters 300 and D305 (see Table 26-42 and Table 26-43).
Section 27.0 "Packaging Information"	Modified the pending TLA packaging page.